GALLIUM SEMICONDUCTOR

GD030

50V, DC - 6.0GHZ, 30W GAN HEMT

FEATURES

Operating Frequency Range: DC to 6.0GHz

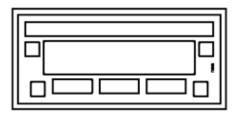
Operating Drain Voltage: +50V

Maximum Output Power (Psat): 50.0W

Maximum Drain Efficiency: 63%

Efficiency-Tuned P3dB Gain: 16.2dB

Bare die shipped in Gel-Pak containers



1.63 x 0.75 mm Die

DESCRIPTION

The GD030 is a 50W (P3dB) unmatched discrete GaN-on-SiC HEMT which operates from DC to 6.0GHz on a 50V supply rail. The wide bandwidth of the GD030 makes it suitable for a variety of applications including cellular infrastructure, radar, communications, and test instrumentation, and can support both CW and pulsed mode of operations.

Bare die are shipped in Gel-Pak containers for safe transport and storage.

TYPICAL PERFORMANCE: POWER TUNED, TA = 25°C

	3.6 GHz	Units
Gain	14.5	dB
Saturated Output Power	50	W
Drain Efficiency	55	%

 $V_D = 50V$, $I_{DQ} = 50mA$

TYPICAL PERFORMANCE: EFFICIENCY TUNED, $T_A = 25^{\circ}C$

	3.6 GHz	Units
Gain	16.2	dB
Saturated Output Power	39	W
Drain Efficiency	63	%

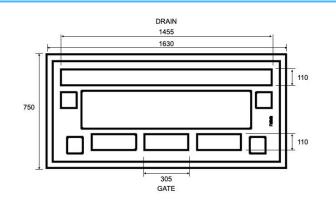
 $V_D = 50V$, $I_{DQ} = 50mA$



ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Breakdown Voltage	>150	BV _{DG} (V)
Gate Source Voltage	-8 to +2	V _{GS} (V)
Operating Voltage	55	V (V)
Junction Temperature	+225	(°C)
Storage Temperature	-65 to +150	(°C)

BLOCK DIAGRAM



ELECTRICAL SPECIFICATIONS: TA = 25°C

Parameter	Min.	Тур.	Max.	Units	Notes
Frequency Range	DC		6000	MHz	
DC Characteristics					
Drain Source Breakdown Voltage		>150		V _{DS} (V)	
Drain Source Leakage Current		0.47		I _{DS} (mA)	
Gate Threshold Voltage		-3 to -1.3		V _{GS} (V)	
Operating Conditions					
Gate Voltage		-2.5		V _G (V)	
Drain Voltage		50		V _D (V)	
Quiescent Drain Current		50		I _{DQ} (mA)	
Thermal Characteristics					
Thermal Resistance		TBD		(°C/W)	